


## Full Material Declaration for attached parts list

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|--|---|
|  | <b>Diotec Semiconductor AG</b>  |
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|  | <b>Declarations authorised by:</b><br>Udo Steinebrunner, Product Manager, - |

Declaration effective from: 1 May 2009 [Approved on 8 March 2016, 08:30 GMT]

## Materials and substances

| Use/Location      | Material group                                  | % w/w of material in the part | Substances in the material                  | CAS Number | % w/w of substance in the material |
|-------------------|---|-------------------------------|---|------------|------------------------------------|
| Chip (die)        | Other inorganic materials                       | 0.25000%                      | Gold  | 7440-57-5  | 8.50000%                           |
|                   |   |                               | ALUMINIUM                                   | 7429-90-5  | 12.00000%                          |
|                   |   |                               | Silicon                                     | 7440-21-3  | 79.50000%                          |
| Encapsulation     | EP (Epoxy resin)                                | 69.02000%                     | Carbon black                                | 1333-86-4  | 0.30000%                           |
|                   |   |                               | ANTIMONY TRIOXIDE                           | 1309-64-4  | 0.80000%                           |
|                   |   |                               | 2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane | 1675-54-3  | 0.99000%                           |
|                   |   |                               | Epoxy resin 89                              | 26335-32-0 | 27.61000%                          |
|                   |   |                               | Quartz sand                                 | 60676-86-0 | 70.30000%                          |
| Inner preparation | Gold  | 0.17000%                      | Gold  | 7440-57-5  | 100.00000%                         |
| Leadfinish        | Tin plating                                     | 1.60000%                      | Tin   | 7440-31-5  | 100.00000%                         |
| Leadframe         | Copper (e.g. copper amounts in cable harnesses) | 28.96000%                     | Copper                                      | 7440-50-8  | 100.00000%                         |

## Attached parts list

| Part number | Part name            | Part Mass | Part Mass UoM |
|-------------|----------------------|-----------|---------------|
| SOT-323     | Diode/Transistor SMD | 0.01      | g             |